



SOT1746-4

HSOP32, plastic, thermal enhanced small outline package; 32 terminals; 0.65 mm pitch; 4.6 mm x 7 mm exposed pad

4 May 2018

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HSOP32
Package style descriptive code	HSOP (heatsink small outline package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	8-3-2018
Manufacturer package code	98ASA00894D

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	11	-	mm
E	package width	-	-	7.5	-	mm
A ₂	package height	-	-	2.33	-	mm
e	nominal pitch	-	-	0.65	-	mm
n ₂	actual quantity of termination	-	-	32	-	A/A



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2. Package outline

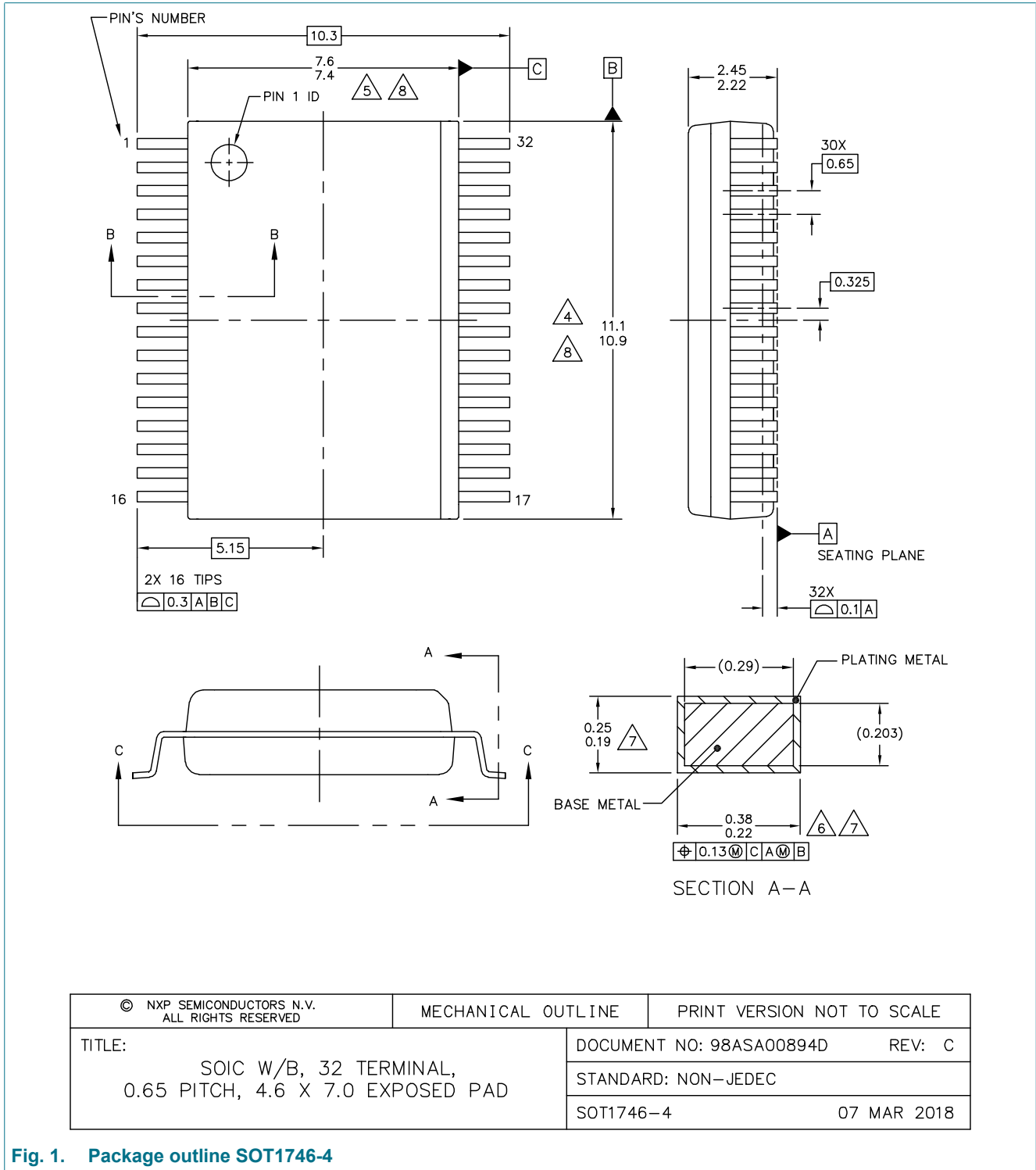
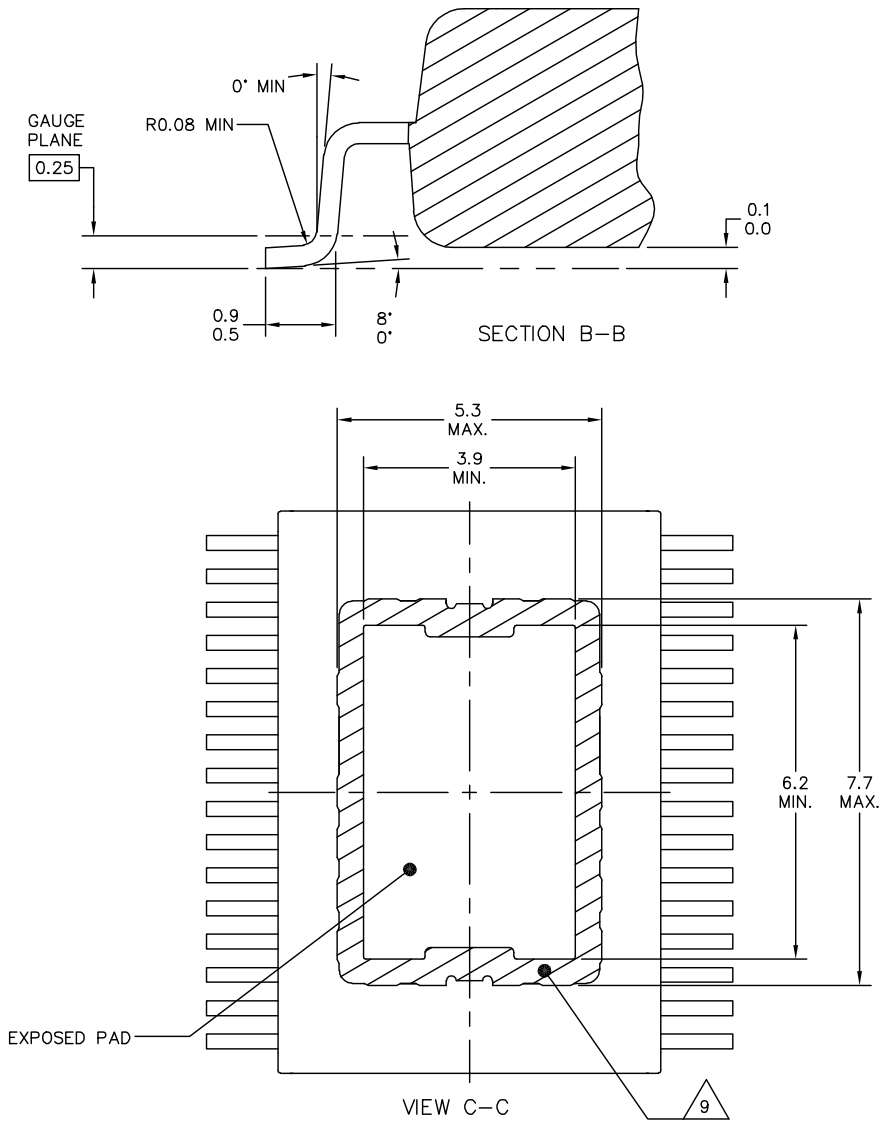


Fig. 1. Package outline SOT1746-4

HSOP32, plastic, thermal enhanced small outline package; 32 terminals; 0.65 mm pitch; 4.6 mm x 7 mm exposed pad



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TITLE: SOIC W/B, 32 TERMINAL, 0.65 PITCH, 4.6 X 7.0 EXPOSED PAD	DOCUMENT NO: 98ASA00894D	REV: C
	STANDARD: NON-JEDEC	
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Fig. 2. Package outline dt1 HSOP32 (SOT1746-4)

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NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. DATUMS B AND C TO BE DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
4. THIS DIMENSION DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS. MOLD FLASH, PROTRUSION OR GATE BURRS SHALL NOT EXCEED 0.15 MM PER SIDE. THIS DIMENSION IS DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
5. THIS DIMENSION DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSIONS. INTER-LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED 0.25 MM PER SIDE. THIS DIMENSION IS DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.4 mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT LESS THAN 0.07 mm.
7. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 mm AND 0.3 mm FROM THE LEAD TIP.
8. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM. THIS DIMENSION IS DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTER-LEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
9. HATCHED AREA TO BE KEEP-OUT ZONE FOR PCB ROUTING.

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Fig. 3. Package outline note HSOP32 (SOT1746-4)

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3. Legal information

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